

1909782-2 ✓ ACTIVE

AMP SLIM

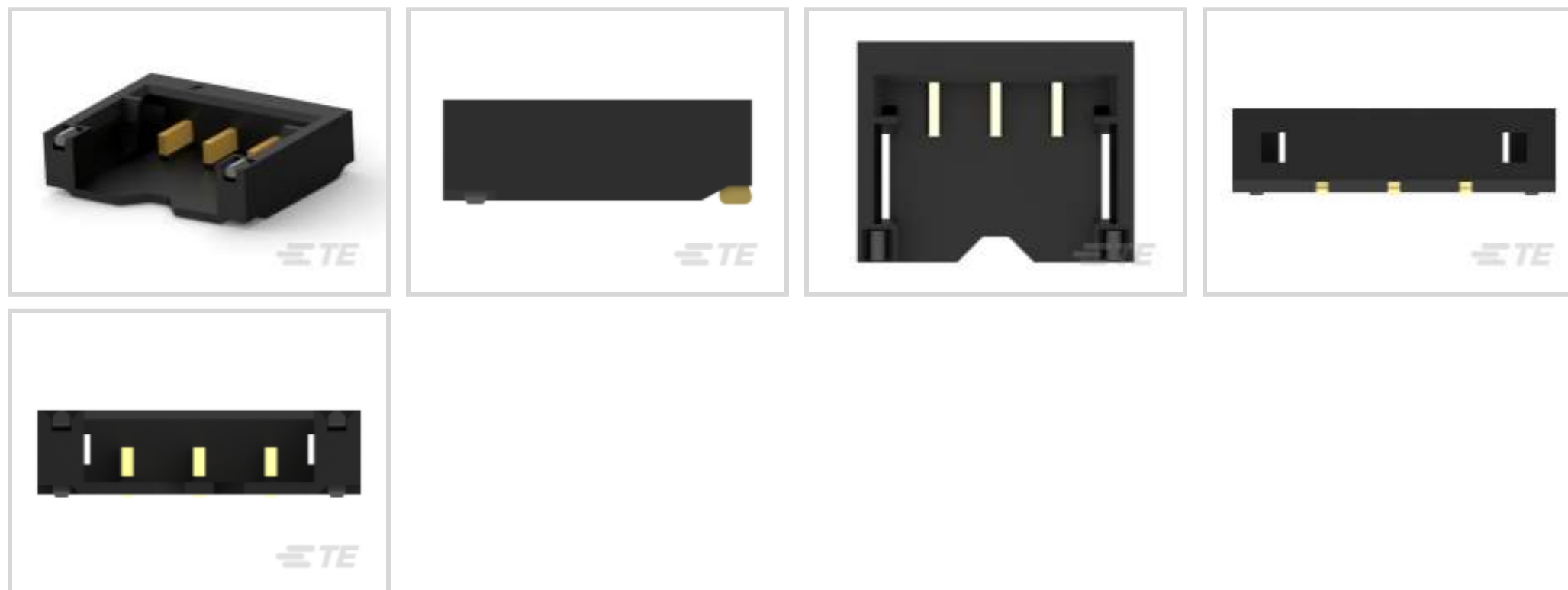
TE Internal #: 1909782-2

PCB Mount Header, Right Angle, Wire-to-Board, 3 Position, 1.2 mm [.047 in] Centerline, Partially Shrouded, Gold Flash, Surface Mount, Signal, AMP SLIM

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Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: **Wire-to-Board**

Number of Positions: **3**

Number of Rows: **1**

Centerline (Pitch): **1.2 mm [.047 in]**

PCB Mount Orientation: **Right Angle**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector System | Wire-to-Board |
| Header Type | Partially Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type | PCB Mount Header |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| Number of Positions | 3 |
| Number of Rows | 1 |
| PCB Mount Orientation | Right Angle |

Electrical Characteristics

| | |
|-------------------|--------|
| Operating Voltage | 50 VAC |
|-------------------|--------|

Body Features

| | |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|



Contact Features

| | |
|---|--|
| PCB Contact Termination Area Plating Material Thickness | 2.54 μm [100 μin] |
| Contact Layout | Inline |
| Contact Mating Area Plating Material Thickness | 1.27 μm [50 μin] |
| PCB Contact Termination Area Plating Material Finish | Matte |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold Flash |
| Contact Type | Pin |
| Contact Current Rating (Max) | 2 A |

Termination Features

| | |
|---|---------------|
| Termination Method to Printed Circuit Board | Surface Mount |
|---|---------------|

Mechanical Attachment

| | |
|--------------------------|--------------|
| Mating Alignment Type | Polarization |
| Mating Retention | With |
| PCB Mount Retention Type | Solder Peg |
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Alignment | Without |
| PCB Mount Retention | With |

Housing Features

| | |
|--------------------|-----------------------------------|
| Housing Material | LCP GF30 (Liquid Crystal Polymer) |
| Centerline (Pitch) | 1.2 mm[.047 in] |

Dimensions

| | |
|------------------|-----------------|
| Connector Length | 5.4 mm[.213 in] |
| Connector Height | 1.4 mm[.055 in] |
| Connector Width | 4.3 mm[.169 in] |

Usage Conditions

| | |
|-----------------------------|---|
| Operating Temperature Range | -25 – 85 $^{\circ}\text{C}$ [-13 – 185 $^{\circ}\text{F}$] |
|-----------------------------|---|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|



Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features

| | |
|--------------------|------|
| Packaging Quantity | 4000 |
| Packaging Type | Reel |

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|---|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Reflow solder capable to 260°C |

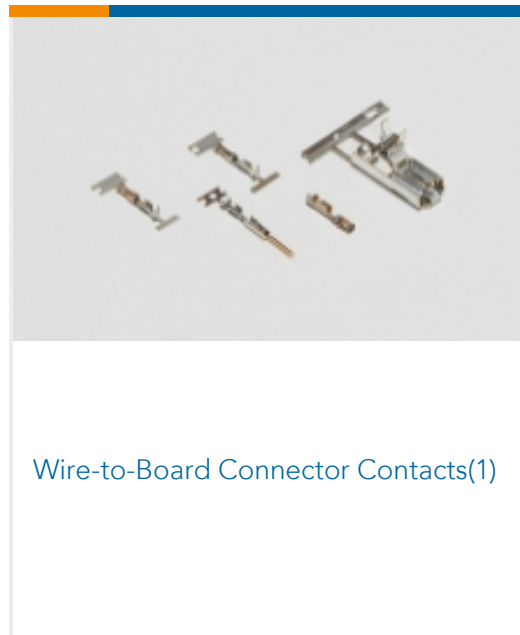
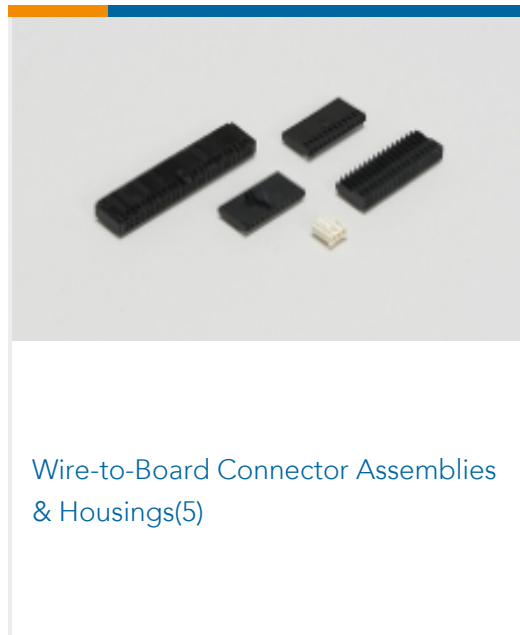
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

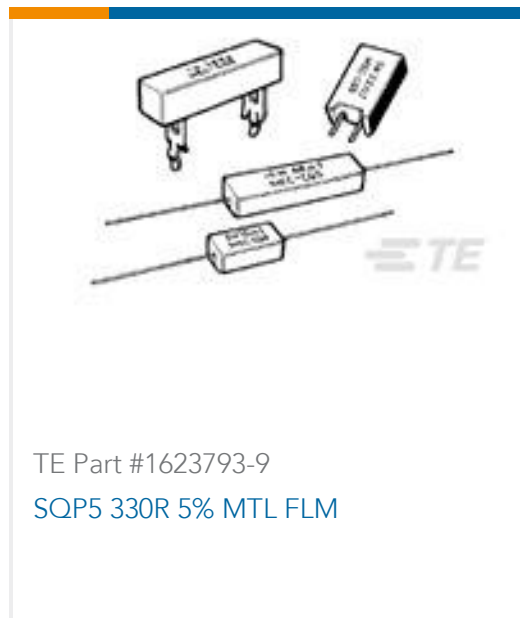
Compatible Parts



Also in the Series | AMP SLIM



Customers Also Bought





Documents

Product Drawings

[BOARD TO WIRE WAFER 1.2MM TOP ENTRY](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_1909782-2_A4.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1909782-2_A4.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_1909782-2_A4.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Application Specification](#)

English